# **Single Input Buffer**

The NLV17SZ16 is a single input Buffer in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

#### **Features**

- Tiny SOT-353 Package
- Source/Sink 24 mA at 3.0 Volts
- Over-Voltage Tolerant Inputs and Outputs
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

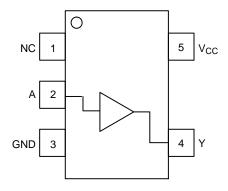


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



# ON Semiconductor®

# www.onsemi.com





MARKING DIAGRAMS

LR = Device Code

M = Date Code\*

= Pb–Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **PIN ASSIGNMENT**

Pin	Function
1	NC
2	IN A
3	GND
4	OUT Y
5	V <sub>CC</sub>

# **FUNCTION TABLE**

A Input	Y Output
L	L
Н	Н

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Para	ameter	Value	Units
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage	Output in High or Low State (Note 2)	$-0.5 \le V_1 \le +7.0$	V
Vo	DC Output Voltage	V <sub>I</sub> < GND	$-0.5 \le V_O \le +7.0$	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>O</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current		-50	mA
I <sub>OUT</sub>	DC Output Sink Current		±50	mA
Icc	DC Supply Current per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground per Supply Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance		350	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C		150	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	Class IC Class A N/A	V
I <sub>Latchup</sub>	Latchup Performance A	bove V <sub>CC</sub> and Below GND at 85°C (Note 6)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
   I<sub>O</sub> Absolute Maximum Rating Must be Obtained.
- 3. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
- 4. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter			Max	Units
V <sub>CC</sub>	DC Supply Voltage	Operations Only Data Retention	1.65 1.5	5.5 5.5	V
V <sub>IN</sub>	DC Input Voltage		0	5.5	V
V <sub>OUT</sub>	DC Output Voltage		0	5.5	V
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

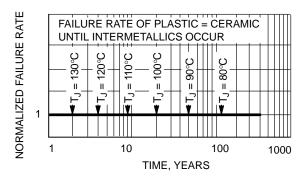


Figure 3. Failure Rate vs. Time Junction Temperature

# DC ELECTRICAL CHARACTERISTICS

	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-55°C ≤ T <sub>A</sub> ≤ 125°C		
Symbol				Min	Тур	Max	Min	Max	Units
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$\begin{split} I_{OH} &= -100 \; \mu A \\ I_{OH} &= -3 \; mA \\ I_{OH} &= -8 \; mA \\ I_{OH} &= -12 \; mA \\ I_{OH} &= -16 \; mA \\ I_{OH} &= -24 \; mA \\ I_{OH} &= -32 \; mA \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>OH</sub>	$\begin{split} I_{OL} &= 100 \; \mu\text{A} \\ I_{OL} &= 4 \; \text{mA} \\ I_{OL} &= 8 \; \text{mA} \\ I_{OL} &= 12 \; \text{mA} \\ I_{OL} &= 16 \; \text{mA} \\ I_{OL} &= 24 \; \text{mA} \\ I_{OL} &= 32 \; \text{mA} \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.0 0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0			1		10	μΑ
Icc	Quiescent Supply Current	V <sub>IN</sub> = 5.5 V or GND	5.5			1		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

			V <sub>CC</sub>		$T_A = 25^{\circ}C$		-55°C ≤ T <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t <sub>PLH</sub> t <sub>PHL</sub>	(Figure 4 and 5)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$\begin{array}{c} 1.65 \\ 1.8 \\ 2.5 \pm 0.2 \\ 3.3 \pm 0.3 \\ 5.0 \pm 0.5 \end{array}$	2.0 2.0 0.8 0.5 0.5	5.3 4.4 2.9 2.1 1.8	11.4 9.5 6.5 4.5 3.9	2.0 2.0 0.8 0.5 0.5	12 10 7.0 4.7 4.1	ns
		$R_L = 500 \Omega, C_L = 50 pF$	$3.3 \pm 0.3$ $5.0 \pm 0.5$	1.5 0.8	2.9 2.4	5.0 4.3	1.5 0.8	5.2 4.5	

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	>4	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 7)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25 30	pF

<sup>7.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

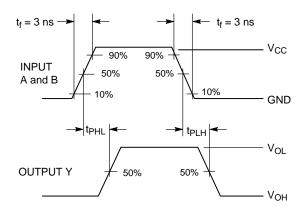
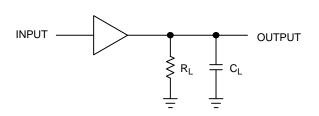


Figure 4. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

### **ORDERING INFORMATION**

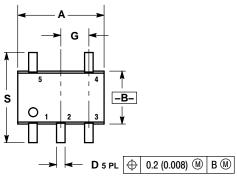
Device	Package	Shipping <sup>†</sup>
NLV17SZ16DFT2G	SC-88A/SC-70-5/SOT-353 (Pb-Free)	3000/Tape & Reel

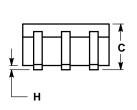
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

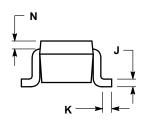
#### PACKAGE DIMENSIONS

# SC-88A (SC-70-5/SOT-353)

CASE 419A-02 **ISSUE L** 







- NOTES:

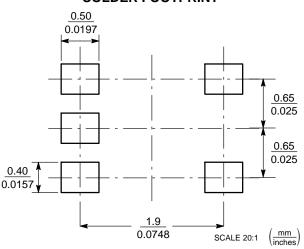
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. 419A-01 OBSOLETE. NEW STANDARD
- 419A-02
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

# **SOLDER FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the (III) are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

# **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative